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FCP20N60 / FCPF20N60 N-Channel SuperFET[®] MOSFET 600 V, 20 A, 190 mΩ

Features

- 650V @ T_{.I} = 150°C
- Typ. R_{DS(on)} = 150 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 75 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 165 pF)
- 100% Avalanche Tested

Applications

- Solar Inverter
- AC-DC Power Supply

August 2014

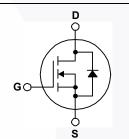
FCP20N60 / FCPF20N60 — N-Channel SuperFET[®] MOSFET

Description

SuperFET[®] MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.







Absolute Maximum Ratings

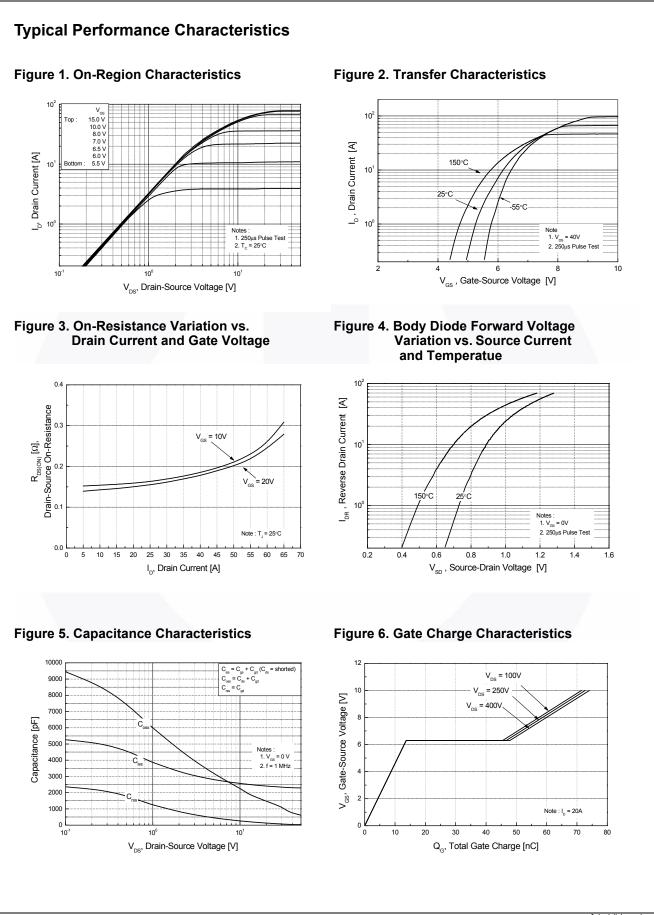
Symbol		Parameter		FCP20N60	FCPF20N60	Unit
V _{DSS}	Drain-Source Voltage			6	V	
ID	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		20 12.5	20* 12.5*	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	60	60 60*	
V _{GSS}	Gate-Source Voltage			±	V	
E _{AS}	Single Pulsed Avalanche Energy			6	mJ	
I _{AR}	Avalanche Current (Note 1) 20		20	А		
E _{AR}	Repetitive Avalanche Energy		(Note 1)	20.8		mJ
dv/dt	Peak Diode Recov	ery dv/dt (Note 3)		4	V/ns	
P _D	Power Dissipation	(T _C = 25°C) - Derate Above 25°C		208 1.67	39 0.3	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range			-55 to	°C	
Τ _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			3	°C	

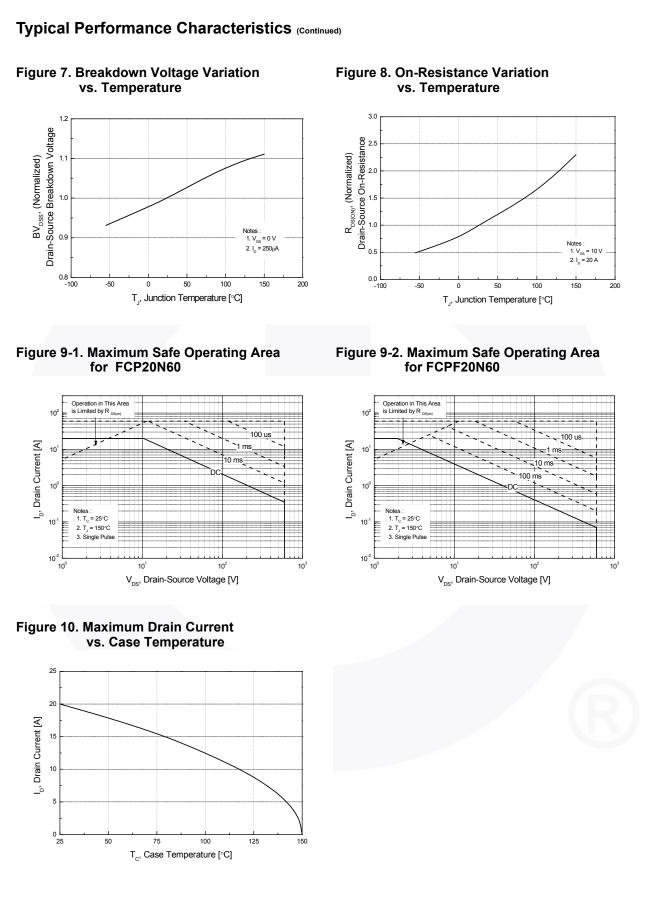
*Drain current limited by maximum junction temperature.

Thermal Characteristics

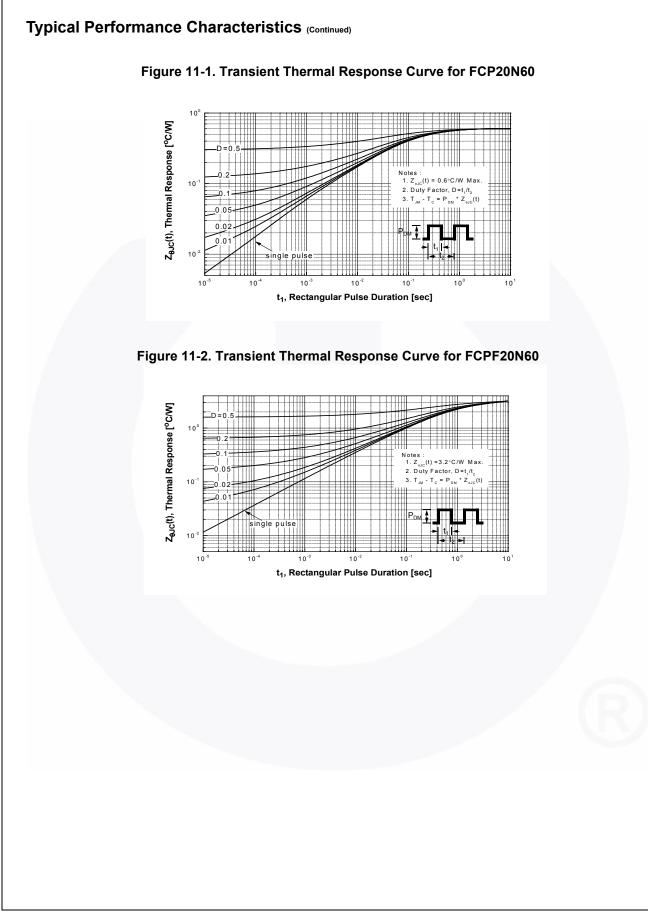
Symbol	Parameter	FCP20N60	FCPF20N60	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.6	3.2	°C/W
R_{\thetaJA}	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

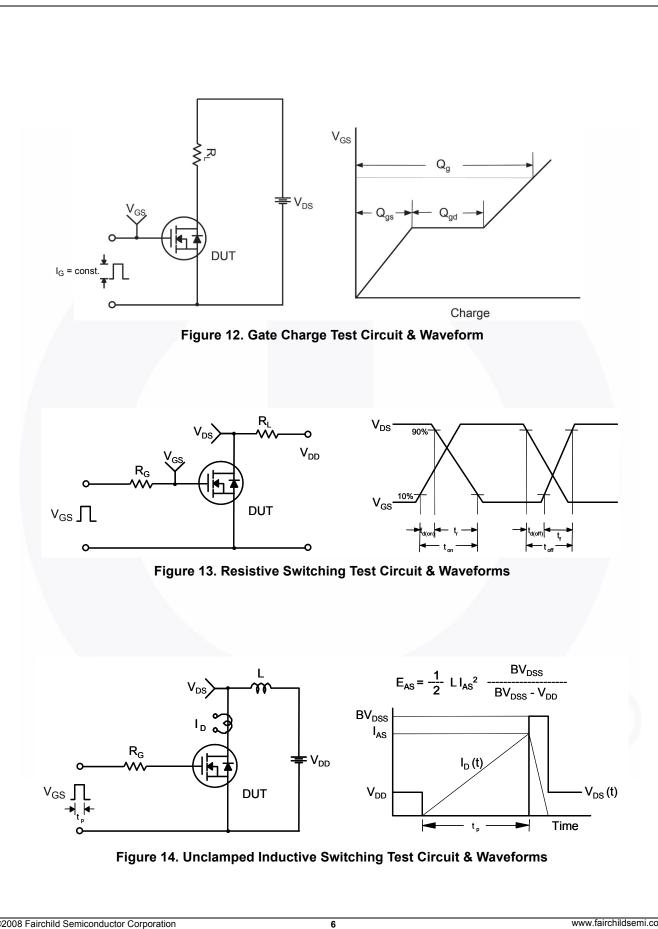
	Top Mark	Packa	age	Packing Method	Reel Size	Тар	e Width	Qua	ntity
60	FCP20N60	TO-2	20	Tube	N/A	N/A		50 units	
		TO-22	20F	Tube	N/A		N/A	50 units	
Chara	cteristics T _C = 2	5ºC unle	ss otł	nerwise noted.					
	Parameter		Test Conditions		Min.	Тур.	Max.	Uni	
eristics	i								
Drain to Source Breakdown Voltage		Ι _D	$\label{eq:ID} \begin{split} &I_D = 250 \; \mu \text{A}, \; \text{V}_{\text{GS}} = 0 \; \text{V}, \; \text{T}_{\text{J}} = 25^{\text{o}}\text{C} \\ &I_D = 250 \; \mu \text{A}, \; \text{V}_{\text{GS}} = 0 \; \text{V}, \; \text{T}_{\text{J}} = 150^{\text{o}}\text{C} \end{split}$			-	-	V	
		Ι _D				650	-	V	
Breakdown Voltage Temperature Coefficient			١ _D	I_D = 250 µA, Referenced to 25°C			0.6	-	V/ºC
Drain-Source Avalanche Breakdown Voltage				V _{GS} = 0 V, I _D = 20 A			700	-	V
Zero Gate Voltage Drain Current				V_{DS} = 600 V, V_{GS} = 0 V		-	-	1	μA
	-					-	-	-	
Gate to E	Body Leakage Current		V	$_{\rm GS} = \pm 30 \text{ V}, \text{ V}_{\rm DS} = 0 \text{ V}$	/	-	-	±100	nA
eristics	i								
Gate Threshold Voltage		V	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		3.0	-	5.0	V	
Static Drain to Source On Resistance		ance				-	0.15	0.19	Ω
Forward Transconductance			V	$V_{\rm DS} = 40 \text{ V}, \text{ I}_{\rm D} = 10 \text{ A}$			17	-	S
haracte	ristics								
		_					2370	3080	pF
			-V	_{DS} = 25 V, V _{GS} = 0 V,	-				pF
			f = 1 MHz				1005	pF	
			$V_{DC} = 480 \text{ V}$ $V_{CC} = 0 \text{ V}$ f = 1 MHz					- 85	pF
	· ·								pF
						-			nC
					-	-		nC	
, and the second s		-	(Note 4)				36	-	nC
	y								
1								105	
Turn-On Rise Time Turn-Off Delay Time						-			ns
			$V_{DD} = 300 \text{ V}, I_D = 20 \text{ A},$		-			ns	
						-			ns
Turn-Off Fall Time						-	65	140	ns
ce Diod	e Characteristics								
Maximum Continuous Drain to Source Diod			ode Fo	orward Current		-	-	20	A
					-	-	60	A	
						-	-	1.4	V
			$V_{GS} = 0 V, I_{SD} = 20 A,$		-	530	-	ns	
Reverse	Recovery Charge		dl	_F /dt = 100 A/µs		-	10.5	-	μC
	eristics Drain to Breakdow Coefficie Drain-So Voltage Zero Gat Gate to E eristics Gate Thr Static Dr Forward Naracte Input Ca Output C Effective Total Gat Gate to E Gate to E Charact Turn-On Turn-Off Turn-Off Turn-Off Maximum Drain to S Reverse	Parameter eristics Drain to Source Breakdown Volta Breakdown Voltage Temperature Coefficient Drain-Source Avalanche Breakdo Voltage Zero Gate Voltage Drain Current Gate to Body Leakage Current eristics Gate Threshold Voltage Static Drain to Source On Resista Forward Transconductance naracteristics Input Capacitance Output Capacitance Coutput Capacitance Effective Output Capacitance Coutput Capacitance Effective Output Capacitance Cotal Gate Charge at 10V Gate to Source Gate Charge Gate to Drain "Miller" Charge Characteristics Turn-On Delay Time Turn-Off Delay Time Turn-Off Fall Time Ce Diode Characteristics Maximum Pulsed Drain to Source	ParametereristicsDrain to Source Breakdown VoltageBreakdown Voltage Temperature CoefficientDrain-Source 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<td>ParameterTest ConditionsMin.eristicsDrain to Source Breakdown Voltage$I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 25^{\circ}C$600Breakdown Voltage Temperature Coefficient$I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^{\circ}C$-Drain-Source Avalanche Breakdown Voltage$V_{GS} = 0 \ V, I_D = 20 \ A$-Zero Gate Voltage Drain Current$V_{DS} = 600 \ V, V_{GS} = 0 \ V$-Gate to Body Leakage Current$V_{GS} = 480 \ V, T_C = 125^{\circ}C$-Gate to Body Leakage Current$V_{GS} = 10 \ V, I_D = 10 \ A$-eristicsGate Threshold Voltage$V_{GS} = 10 \ V, I_D = 10 \ A$-Forward Transconductance$V_{DS} = 480 \ V, I_D = 10 \ A$-ParacteristicsInput Capacitance$V_{DS} = 25 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$-Output Capacitance$V_{DS} = 25 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$-Output Capacitance$V_{DS} = 480 \ V, I_D = 10 \ A$-Output Capacitance$V_{DS} = 480 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$-Gate to Source Gate Charge$V_{DS} = 10 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$-Gate to Source Gate Charge$V_{DS} = 480 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$-Gate to Drain "Miller" Charge$V_{DS} = 10 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$-Gate to Drain "Miller" Charge$V_{DS} = 10 \ V, V_{GS} = 0 \ V, I_D = 20 \ A, I_$</td> <td>$\begin{tabular}{ c c c c c } \hline Parameter & Test Conditions & Min. Typ. \\ \hline eristics \\ \hline Prain to Source Breakdown Voltage & I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 25^{\circ}C & 600 & - \\ \hline I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^{\circ}C & - & 650 \\ \hline Breakdown Voltage Temperature & I_D = 250 \ \mu A, Referenced to 25^{\circ}C & - & 0.6 \\ \hline Drain-Source Avalanche Breakdown & V_{GS} = 0 \ V, I_D = 20 \ A & - & 700 \\ \hline V_{DS} = 600 \ V, V_{GS} = 0 \ V & - & - & - & \\ \hline V_{DS} = 600 \ V, V_{CS} = 0 \ V & - & - & - & \\ \hline V_{DS} = 480 \ V, \ T_C = 125^{\circ}C & - & - & - & \\ \hline Coefficient & V_{GS} = 40 \ V, \ T_D = 0 \ A & - & - & - & \\ \hline Coefficient & V_{GS} = 10 \ V, \ V_{DS} = 0 \ V & - & - & - & \\ \hline Coefficient & V_{GS} = 10 \ V, \ V_{DS} = 0 \ V & - & - & - & \\ \hline Coefficient & V_{CS} = 10 \ V, \ V_{DS} = 10 \ A & - & 0.15 \\ \hline Forward Transconductance & V_{GS} = 10 \ V, \ I_D = 10 \ A & - & 0.15 \\ \hline Forward Transconductance & V_{DS} = 40 \ V, \ I_D = 10 \ A & - & 17 \\ \hline naracteristics & & & & \\ \hline Input \ Capacitance & V_{DS} = 40 \ V, \ I_D = 10 \ A & - & 17 \\ \hline naracteristics & & & & & \\ \hline Input \ Capacitance & V_{DS} = 480 \ V, \ V_{CS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 480 \ V, \ V_{DS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 480 \ V, \ U_{DS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 0 \ V to 400 \ V, \ V_{CS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 10 \ V \ O_{DS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Characteristics & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Fiel \ Time & & & \\ \hline Tum-On \ Fiel \ Time & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Fiel \ Time & & \\ \hline Tum-On \ Fiel \ Time & & \\ \hline Tum-On \ Delay \ Time & & \\ \hline Tum-On \ Fiel \ Time & & \\ \hline$</td> <td>$\begin{tabular}{ c c c c c } \hline Parameter & Test Conditions & Min. Typ. Max. \\ \hline Fristics \\ \hline Prain to Source Breakdown Voltage \\ \hline Drain to Source Breakdown Voltage Temperature \\ l_{D} = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_{J} = 25^{O} \ C & 600 & - & - & \\ l_{D} = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_{J} = 150^{\circ} \ C & - & 650 & - & \\ \hline Breakdown Voltage Temperature \\ l_{D} = 250 \ \mu A, \ Referenced to 25^{\circ} \ C & - & 0.6 & - & \\ \hline Drain-Source Avalanche Breakdown \\ V_{GS} = 0 \ V, \ l_{D} = 20 \ A & - & 700 & - & \\ \hline Torin Source Avalanche Breakdown \\ V_{OS} = 0 \ V, \ V_{OS} = 0 \ V & - & - & 1 & \\ \hline V_{DS} = 480 \ V, \ T_{C} = 125^{\circ} \ C & - & - & 10 & \\ \hline Gate to Body Leakage Current & V_{GS} = 480 \ V, \ l_{D} = 250 \ \mu A & 3.0 & - & 5.0 & \\ \hline Static Drain to Source On Resistance & V_{GS} = 10 \ V, \ l_{D} = 10 \ A & - & 0.15 & 0.15 & \\ \hline Forward Transconductance & V_{OS} = 25 \ V, \ V_{GS} = 0 \ V, \ l_{D} = 10 \ A & - & 17 & - & \\ \hline haracteristics & &$</td>	eristicsDrain to Source Breakdown Voltage $I_D = 250 \ \mu$ A, $V_{GS} = 0 \ V$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, $V_{GS} = 0 \ V$ Drain-Source Avalanche Breakdown Voltage $V_{GS} = 0 \ V$, $I_D = 20 \ A$ Zero Gate Voltage Drain Current $V_{DS} = 600 \ V$, $V_{GS} = 0 \ V$ Gate to Body Leakage Current $V_{GS} = 480 \ V$, $T_C = 1250 \ \mu$ AGate Threshold Voltage $V_{GS} = \pm 30 \ V$, $V_{DS} = 0 \ V$ Gate Threshold Voltage $V_{GS} = \pm 30 \ V$, $V_{DS} = 0 \ V$ Gate Threshold Voltage $V_{GS} = \pm 10 \ V$, $I_D = 10 \ A$ Forward Transconductance $V_{DS} = 40 \ V$, $I_D = 10 \ A$ ParacteristicsInput CapacitanceOutput Capacitance $V_{DS} = 480 \ V$, $V_{GS} = 0 \ V$,Gate to Source Gate Charge $V_{DS} = 480 \ V$, $V_{GS} = 0 \ V$ Output Capacitance $V_{DS} = 480 \ V$, $V_{GS} = 0 \ V$ Output Capacitance $V_{DS} = 480 \ V$, $V_{GS} = 0 \ V$ Gate to Source Gate Charge $V_{GS} = 10 \ V$ Characteristics $V_{DS} = 480 \ V$, $I_D = 20 \ A$ Turn-On Delay 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10 AForward TransconductanceVDS = 25 V, VGS = 0 V, f = 1 MHzPopulation CapacitanceOutput CapacitanceVDS = 480 V, VGS = 0 V, f = 1 MHzOutput CapacitanceVDS = 480 V, VGS = 0 V, f = 1 MHzCotal Gate Charge at 10VVDS = 480 V, VGS = 0 V, f = 1 MHzCate to Drain "Miller" ChargeVDS = 480 V, ID = 20 A, VGS = 10 VCate to Drain "Miller" ChargeVDS = 300 V, ID = 20 A, VGS = 10 VConde CharacteristicsTurn-On Rise Time Turn-Off Fall TimeVDS = 300 V, ID = 20 A, VGS = 10 V, Cols = 10 V, RG = 25 Ω (Note 4)Cobide CharacteristicsMaximum Continuous Drain to Source Diode Forward Current Maximum Pulsed Drain to Source Diode Forward Current Maximum Pulsed Drain to Source Diode Forward Current Drain to Source Diode Forward Current Maximum Pulsed Drain to	ParameterTest ConditionsMin.eristicsDrain to Source Breakdown Voltage $I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 25^{\circ}C$ 600Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^{\circ}C$ -Drain-Source Avalanche Breakdown Voltage $V_{GS} = 0 \ V, I_D = 20 \ A$ -Zero Gate Voltage Drain Current $V_{DS} = 600 \ V, V_{GS} = 0 \ V$ -Gate to Body Leakage Current $V_{GS} = 480 \ V, T_C = 125^{\circ}C$ -Gate to Body Leakage Current $V_{GS} = 10 \ V, I_D = 10 \ A$ -eristicsGate Threshold Voltage $V_{GS} = 10 \ V, I_D = 10 \ A$ -Forward Transconductance $V_{DS} = 480 \ V, I_D = 10 \ A$ -ParacteristicsInput Capacitance $V_{DS} = 25 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$ -Output Capacitance $V_{DS} = 25 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$ -Output Capacitance $V_{DS} = 480 \ V, I_D = 10 \ A$ -Output Capacitance $V_{DS} = 480 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$ -Gate to Source Gate Charge $V_{DS} = 10 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$ -Gate to Source Gate Charge $V_{DS} = 480 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$ -Gate to Drain "Miller" Charge $V_{DS} = 10 \ V, V_{GS} = 0 \ V, I_D = 10 \ A$ -Gate to Drain "Miller" Charge $V_{DS} = 10 \ V, V_{GS} = 0 \ V, I_D = 20 \ A, I_$	$\begin{tabular}{ c c c c c } \hline Parameter & Test Conditions & Min. Typ. \\ \hline eristics \\ \hline Prain to Source Breakdown Voltage & I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 25^{\circ}C & 600 & - \\ \hline I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^{\circ}C & - & 650 \\ \hline Breakdown Voltage Temperature & I_D = 250 \ \mu A, Referenced to 25^{\circ}C & - & 0.6 \\ \hline Drain-Source Avalanche Breakdown & V_{GS} = 0 \ V, I_D = 20 \ A & - & 700 \\ \hline V_{DS} = 600 \ V, V_{GS} = 0 \ V & - & - & - & \\ \hline V_{DS} = 600 \ V, V_{CS} = 0 \ V & - & - & - & \\ \hline V_{DS} = 480 \ V, \ T_C = 125^{\circ}C & - & - & - & \\ \hline Coefficient & V_{GS} = 40 \ V, \ T_D = 0 \ A & - & - & - & \\ \hline Coefficient & V_{GS} = 10 \ V, \ V_{DS} = 0 \ V & - & - & - & \\ \hline Coefficient & V_{GS} = 10 \ V, \ V_{DS} = 0 \ V & - & - & - & \\ \hline Coefficient & V_{CS} = 10 \ V, \ V_{DS} = 10 \ A & - & 0.15 \\ \hline Forward Transconductance & V_{GS} = 10 \ V, \ I_D = 10 \ A & - & 0.15 \\ \hline Forward Transconductance & V_{DS} = 40 \ V, \ I_D = 10 \ A & - & 17 \\ \hline naracteristics & & & & \\ \hline Input \ Capacitance & V_{DS} = 40 \ V, \ I_D = 10 \ A & - & 17 \\ \hline naracteristics & & & & & \\ \hline Input \ Capacitance & V_{DS} = 480 \ V, \ V_{CS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 480 \ V, \ V_{DS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 480 \ V, \ U_{DS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 0 \ V to 400 \ V, \ V_{CS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Effective Output \ Capacitance & V_{DS} = 10 \ V \ O_{DS} = 0 \ V, \ I = 1 \ MHz & - & 665 \\ \hline Characteristics & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Fiel \ Time & & & \\ \hline Tum-On \ Fiel \ Time & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Delay \ Time & & & \\ \hline Tum-On \ Fiel \ Time & & \\ \hline Tum-On \ Fiel \ Time & & \\ \hline Tum-On \ Delay \ Time & & \\ \hline Tum-On \ Fiel \ Time & & \\ \hline$	$\begin{tabular}{ c c c c c } \hline Parameter & Test Conditions & Min. Typ. Max. \\ \hline Fristics \\ \hline Prain to Source Breakdown Voltage \\ \hline Drain to Source Breakdown Voltage Temperature \\ l_{D} = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_{J} = 25^{O} \ C & 600 & - & - & \\ l_{D} = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_{J} = 150^{\circ} \ C & - & 650 & - & \\ \hline Breakdown Voltage Temperature \\ l_{D} = 250 \ \mu A, \ Referenced to 25^{\circ} \ C & - & 0.6 & - & \\ \hline Drain-Source Avalanche Breakdown \\ V_{GS} = 0 \ V, \ l_{D} = 20 \ A & - & 700 & - & \\ \hline Torin Source Avalanche Breakdown \\ V_{OS} = 0 \ V, \ V_{OS} = 0 \ V & - & - & 1 & \\ \hline V_{DS} = 480 \ V, \ T_{C} = 125^{\circ} \ C & - & - & 10 & \\ \hline Gate to Body Leakage Current & V_{GS} = 480 \ V, \ l_{D} = 250 \ \mu A & 3.0 & - & 5.0 & \\ \hline Static Drain to Source On Resistance & V_{GS} = 10 \ V, \ l_{D} = 10 \ A & - & 0.15 & 0.15 & \\ \hline Forward Transconductance & V_{OS} = 25 \ V, \ V_{GS} = 0 \ V, \ l_{D} = 10 \ A & - & 17 & - & \\ \hline haracteristics & & & & & & & & & & & & & & & & & & &$





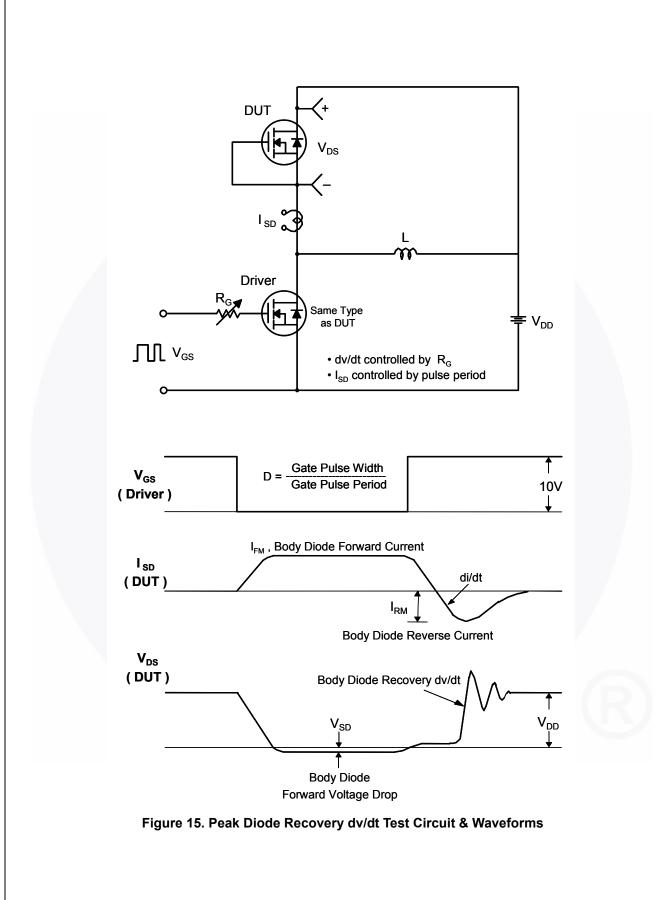
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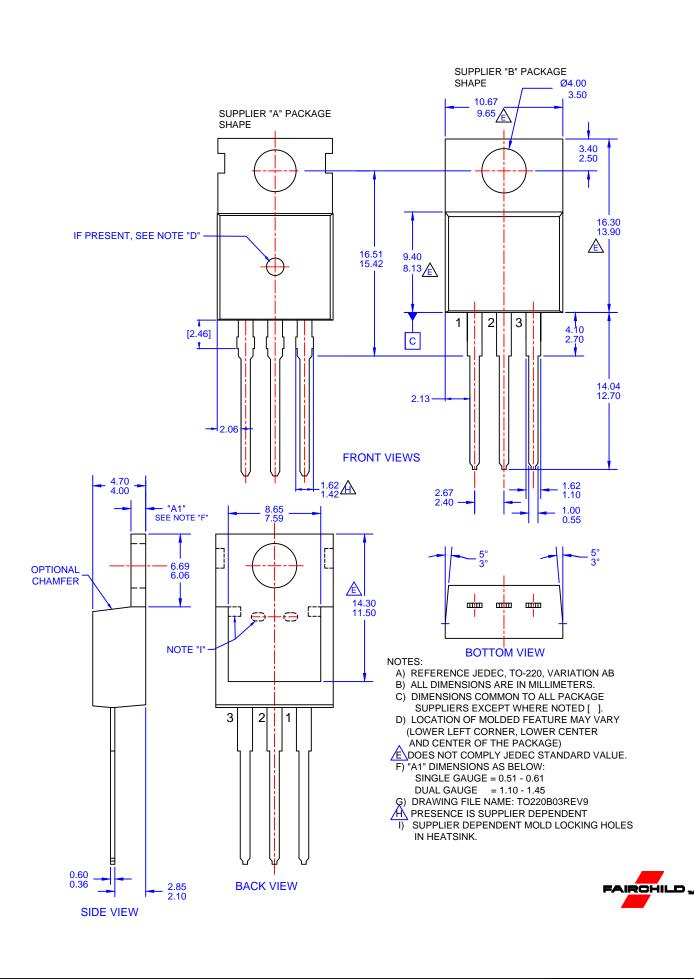


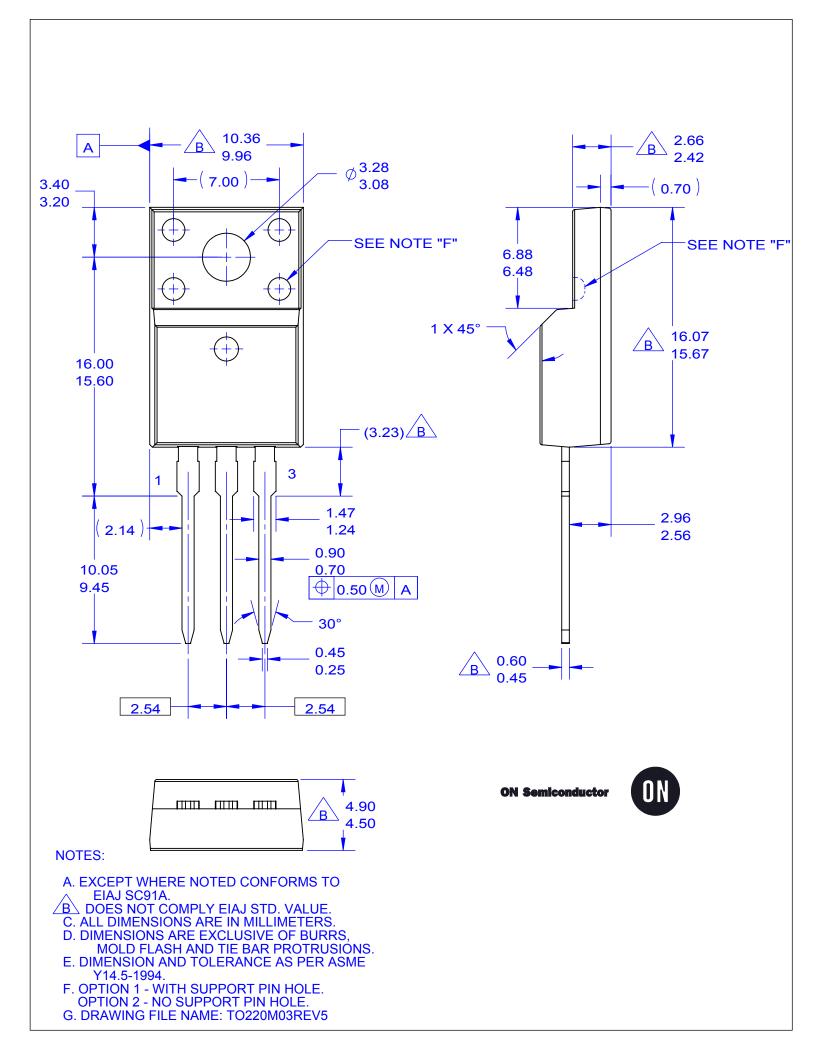


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